a second mounting head section for successively picking up the components at the other of the component supply tables and thereafter successively mounting the picked-up components onto the board,

wherein each of the first and second mounting head sections is independently moveable between the component supply table and the board.

9. The component mounting apparatus as claimed in claim 8, wherein said each of said first and second mounting head sections is moveable in two directions which are perpendicular to each other and are parallel to a surface of the board.

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10. The component mounting apparatus as claimed in claim 8, further comprising a controller for mutually controlling the first and second mounting head sections in accordance with a timing at which, when one of the first and second mounting head sections carries out a component picking-up operation for picking-up the components from the component supply table, the other of the first and second mounting head sections carries out a component mounting operation for mounting the picked-up components onto the board.

11. The component mounting apparatus as claimed in claim 9, further comprising a controller for mutually controlling the first and second mounting head sections in accordance with a timing

at which, when one of the first and second mounting head sections carries out a component picking-up operation for picking-up the components from the component supply table, the other of the first and second mounting head sections carries out a component mounting operation for mounting the picked-up components onto the board.

12. The component mounting apparatus as claimed in claim 8, wherein one of the first and second mounting head sections has a plurality of component suction nozzles for sucking the components at one time.

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13. The component mounting apparatus as claimed in claim 9, wherein one of the first and second mounting head sections has a plurality of component suction nozzles for sucking the components at one time.

14. The component mounting apparatus as claimed in claim 10, wherein one of the first and second mounting head sections has a plurality of component suction nozzles for sucking the components at one time.

15. The component mounting apparatus as claimed in claim 11, wherein one of the first and second mounting head sections has a plurality of component suction nozzles for sucking the components at one time.

16. A component mounting method comprising processes of:

picking up, by a first mounting head section, components from one of a pair of component supply tables on which components are accommodated and which are arranged on both sides of a board mounting position where a board is positioned, the first mounting head section successively picking up the components at one of the component supply tables;

thereafter successively mounting the components picked-up by the first mounting head section onto the board;

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picking up, by a second mounting head section, components from the other of the pair of component supply tables, the second mounting head section successively picking up the components at the other of the component supply tables; and

thereafter successively mounting the components picked-up by the second mounting head section onto the board, wherein the picking-up and mounting processes of the first mounting head section and the picking-up and mounting processes of the second mounting head section are independently carried out, and the first mounting head section and the second mounting head section is each independently moveable between the component supply table and the board.

17. The component mounting method as claimed in claim 16, wherein the picking-up process of the first mounting head